

**Quantitative Analysis of Room Temperature Grain Growth Kinetics
in Copper Thin Films through High Resolution X-ray Diffraction**

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In this talk we describe a set of experiments where room temperature recrystallization kinetics in electroplated Cu films were monitored using high resolution X-ray diffraction. These experiments yielded orientation-specific, quantitative, data on how plating variables influence the recrystallization rate of electroplated films. Our results indicate that the recrystallization rate is primarily driven by the amount of initial 111 texture.